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Tetsuo Yamada, Keigo Nagao, Chisen Hashimoto
Additional name(s) of conveying party(ies) attached?
MAD 7-31-02 [ ] Yes [X] No

2. Name and address of receiving party(ies)
Name: UBE Electronics, Ltd.
Internal Address:
Street Address: 2023-2, Mugigawa, Okubun, Ohmine-cho, Mine-shi, Yamaguchi, Japan
City: State: Zip:
Additional name(s) & address(es) attached? [ ] Yes [X] No

3. Nature of conveyance:
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Execution Date: July 18, 2002

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:
A. Patent Application No.(s) 10/142,233 B. Patent No.(s)
Additional numbers attached? [ ] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Ronald R. Santucci
Internal Address: Frommer Lawrence & Haug LLP
Street Address: 745 Fifth Avenue
City: New York State: New York Zip: 10151

6. Total number of applications and patents involved ..... 1
7. Total fee (37 CFR 3.41) ..... \$ 40
[X] Enclosed
[ ] Authorized to be charged to deposit account #50-0320
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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Ronald R. Santucci, Reg. No. 28,988
Signature: [Handwritten Signature]
07/26/02
Name of Person Signing Signature Total number of pages including cover sheet, attachments, and document): 2

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08/02/2002 MBERHE 00000101 10142233
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PATENT REEL: 013154 FRAME: 0264

**INVENTION/PATENT APPLICATION ASSIGNMENT**  
**FROM INVENTOR(S) TO COMPANY**

WHEREAS I/WE Tetsuo YAMADA of Yamaguchi, Japan, Keigo NAGAO of Yamaguchi, Japan, Chisen HASHIMOTO of Yamaguchi, Japan, respectively, have made a certain new and useful invention as set forth in an application for United States Letters Patent, entitled: **THIN FILM BULK ACOUSTIC RESONATOR AND METHOD OF PRODUCING THE SAME**, executed by us on the date of execution of this document, as shown below, and filed concurrently herewith;  
 OR  
 for which an application for United States Letters Patent was filed on **May 9, 2002**, and identified by United States Serial No. 10/142,233 ;

AND WHEREAS, UBE ELECTRONICS, LTD. a corporation of the State of Japan and having an address of 2023-2, Mugigawa, Okubun, Ohmine-cho, Mine-shi, Yamaguchi, Japan, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any and all Letters Patent of the United States and foreign countries that may be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt for and sufficiency of which is hereby acknowledged, We do hereby sell, assign, transfer and set over unto said assignee, its legal representatives, successors, and assigns, the entire right, title and interest in and to said invention as set forth in the above-mentioned application, including any continuations, continuations-in-part, divisions, reissues, re-examinations or extensions thereof, and in and to any and all patents of the United States and foreign countries that may be issued for said invention;

UPON SAID CONSIDERATIONS, We hereby agree with the said assignee that We will not execute any writing or do any act whatsoever conflicting with these presents, and that We will, at any time upon request, without further or additional consideration but at the expense of said assignee, execute such additional assignments and other writings and do such additional acts as said assignee may deem necessary or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuations, continuations-in-part, reexamined, reissued, or extended Letters Patent of the United States or of any and all foreign countries on said invention, and in enforcing any rights or causes of action accruing as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of the assigns and legal representatives of assignor and assignee;

AND We request the Commissioner of Patents and Trademarks to issue any Letters Patent of the United States that may be issued for said invention to said assignee, its legal representatives, successors or assigns, as the sole owner of the entire right, title and interest in and to said patent and the invention covered thereby.

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 July 18, 2002  
 Date  
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 Signature Tetsuo Yamada *Tetsuo Yamada*  
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 Signature Keigo Nagao *Keigo Nagao*  
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 Signature Chisen Hashimoto *Chisen Hashimoto*  
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